

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	HONGJUN YU	04/25/2018
RECEIVING PARTY DATA		
Name:	SEMICONDUCTOR MANUFACTURING INTERNATIONAL (SHANGHAI) CORPORATION	
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City:	BEIJING	
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PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	15962904	
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NAME OF SUBMITTER:	JING ZHENG, REG. NO. 75,830	

SIGNATURE:	/Jing Zheng, Reg. No. 75,830/
DATE SIGNED:	04/25/2018
Total Attachments: 1 source=SMIC00126US_Assignment_EF#page1.tif	

CLIENT REFERENCE NO.: 2016-01179-SH-US

ATTORNEY DOCKET NO.: SMIC00126 US

ASSIGNMENT

For good and valuable consideration, receipt of which is hereby acknowledged, I

Hongjun YU of 18 Zhangjiang Road
Pudong New Area
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hereby sell, assign and transfer to **Semiconductor Manufacturing International (Shanghai) Corporation**, having a place of business at 18 Zhangjiang Road, Pudong New Area, Shanghai, P.R.C. 201203, and, **Semiconductor Manufacturing International (Beijing) Corporation**, having a place of business at 18 Wenchang Road, Beijing Economic-Technological Development Area, Beijing, China, 100176, its successors and assigns, the entire right, title and interest throughout the world in the invention entitled

A MICROPHONE AND MANUFACTURE THEREOF

for which I have executed a United States patent application on or about the date of this assignment, and all patent applications and patents of every country for said invention, including divisionals, reissues, continuations and extensions thereof, and all rights of priority resulting from the filing of said applications; I authorize the above-named assignee to apply for patents of foreign countries for said invention, and to claim all rights of priority without further authorization from me; I agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignee, its successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in all countries; and I request that the United States Patent and Trademark Office issue all patents granted for said invention to the above-named assignee, its successors and assigns.

Executed this 15 day of Apr, 2018.

俞宏俊
Hongjun YU

WITNESSED: 石磊

Signature 俞宏俊

Date 2018-4-15

Type or print name of witness